<u>**FOR IMMEDIATE RELEASE**</u>

EV GROUP JOINS GEORGIA TECH 3D SYSTEMS PACKAGING RESEARCH CENTER

EVG's State-of-the-Art Wafer Bonding and Lithography Equipment and Know-How to Be Leveraged in Silicon and Glass Interposer Research Program

ST. FLORIAN, Austria, July 6, 2011 – EV Group (EVG), a leading supplier of wafer bonding and lithography equipment for the MEMS, nanotechnology and semiconductor markets, today announced its engagement with the Georgia Institute of Technology 3D Systems Packaging Research Center (GT PRC) as a Manufacturing Infrastructure Member. Through the consortia membership, EVG's state-of-the-art temporary bonding and debonding, chip-to-wafer bonding and lithography technology and associated product and process know-how will be included in the PRC's Silicon and Glass Interposer Industry (SiGI) Consortium research program.

Launched in February, the SiGI Consortium is pursuing, with global partners, development of ultra-thin glass interposers – the intermediate layers typically used for routing electrical interconnections – at 10x lower cost than wafer-based silicon interposers. Participating in the consortium will enable EVG and other supply-chain providers to understand the applicability of EVG's manufacturing equipment and solutions for ultra-miniaturized device and systems packaging applications using through-silicon vias (TSVs).

"We are delighted to welcome EVG as a new industry member," commented PRC Director Professor Rao R. Tummala, Ph.D. "The company's advanced, production-proven equipment and comprehensive process know-how will enable EVG to greatly contribute to our pioneering system-on-package technology research and development."

Paul Lindner, EVG's executive technology director, stated, "EVG co-founded the EMC-3D Semiconductor and Materials Consortium in 2006, with the mission to develop cost-effective and manufacturable TSVs for advanced semiconductors. Through membership in and collaboration with the PRC, we aim to further develop technologies that will make silicon and glass interposers with TSVs a truly affordable packaging solution." Lindner further noted that EVG's membership in the GT PRC strengthens the relationship between the two entities, as the Georgia Tech Institute of Technology has been using EVG equipment for close to a decade.

The Georgia Tech PRC's stated goal is to explore technologies in partnership with industry, addressing challenges five to 10 years ahead of the manufacturing need and connecting discoveries in an effort to eliminate the so-called "valley of death" between university research and industry needs. Similarly, through its Triple-I philosophy (invent, innovate, implement), EVG's ongoing mission is "to be the first in exploring new techniques and serving next-generation applications of micro and nano fabrication technologies to enable its customers to successfully commercialize their new product ideas." This synergy of vision and mission makes EVG a well-suited addition to the PRC's membership.

About the Georgia Institute of Technology 3D Systems Packaging Research Center
The 3D Systems Packaging Research Center (PRC), housed in the Manufacturing Research Center building on the Georgia Tech campus, was established in 1994 as a U.S. National Science Foundation (NSF) Engineering Research Center (ERC). It has been the largest and most comprehensive global research center dedicated to integration of leading–edge research, cross-discipline education of more than 100 students and industry collaborations with 70 companies in US, Europe, Japan and Korea in System-on-Package (SOP) and other emerging microsystems packaging technologies.
More information is available at http://www.prc.gatech.edu/index.shtml.

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About EV Group
EV Group (EVG) is a world leader in wafer-processing solutions for semiconductor, MEMS and nanotechnology applications. Through close collaboration with its global customers, the company implements its flexible manufacturing model to develop reliable, high-quality, low-cost-of-ownership systems that are easily integrated into customers' fab lines. Key products include wafer bonding, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners and inspection systems.

In addition to its dominant share of the market for wafer bonders, EVG holds a leading position in NIL and lithography for advanced packaging and MEMS. Along these lines, the company co-founded the EMC-3D consortium in 2006 to create and help drive implementation of a cost-effective through-silicon via (TSV) process for major ICs and MEMS/sensors. Other target semiconductor-related markets include silicon-on-insulator (SOI), compound semiconductor and silicon-based power-device solutions.

Founded in 1980, EVG is headquartered in St. Florian, Austria, and operates via a global customer support network, with subsidiaries in Tempe, Ariz.; Albany, N.Y.; Yokohama and Fukuoka, Japan; Seoul, Korea and Chung-Li, Taiwan. The company's unique Triple i-approach (invent - innovate - implement) is supported by a vertical integration, allowing EVG to respond quickly to new technology developments, apply the technology to manufacturing challenges and expedite device manufacturing in high volume. More information is available at www.EVGroup.com.

Contacts:

Clemens Schütte
Director, Marketing and Communications
EV Group
Tel: +43 7712 5311 0
E-mail: Marketing@EVGroup.com

Marie Labrie
CEO
MCA, Inc.
Tel: +1.650.968.8900, ext. 119
E-mail: mlabrie@mcapr.com

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